

APPROVAL SHEET

RFBPF Series – 2012(0805)- RoHS Compliance

MULTILAYER CERAMIC BAND PASS FILTER

Halogens Free Product

2.4 GHz ISM Band Working Frequency

P/N: RFBPF2012080AFT

*Contents in this sheet are subject to change without prior notice.

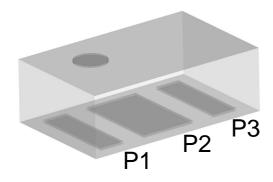
FEATURES

- 1. Miniature footprint: 2.0 X 1.2 X 0.8 mm³
- 2. Low Insertion Loss
- 3. High Rejection on GSM Bands
- 4. High attenuation on 2170 MHz & 2nd harmonic suppressed
- 5. LTCC process

APPLICATIONS

- 1. 2.4GHz ISM band RF applications
- 2. Bluetooth, Wireless LAN 802.11b/g/n, HomeRF

CONSTRUCTION



PIN	Connection		
1	Input port		
2	GND		
3	Output port		

DIMENSIONS

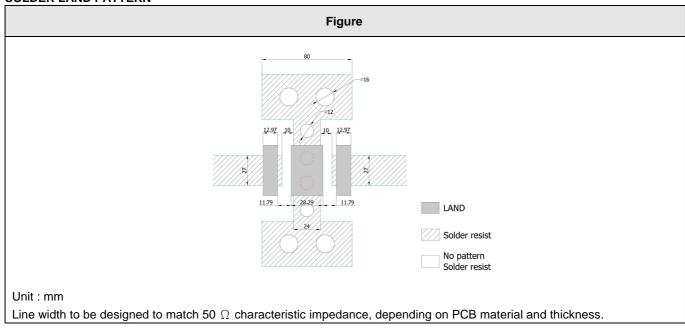
Figure	Symbol	Dimension (mm)
L B C D E	L	2.00 ± 0.15
	W	1.25 ± 0.10
F	Т	0.80 ± 0.10
T T	А	0.95 ± 0.10
	В	0.275 ± 0.10
	С	0.25 ± 0.10
	D	0.60 ± 0.10
	Е	0.175 ± 0.10
	F	0.15 ± 0.10



ELECTRICAL CHARACTERISTICS

RFBPF2012080AFT	Specification		
Frequency range	2450± 50 MHz		
Insertion Loss	1.8 dB at 25°C		
IIISEITIOIT LOSS	2.0 dB at -40°C ~ +85°C		
VSWR	2.0 max		
Impedance	50 Ω		
	30@ 824~ 915MHz		
	30@ 1545~ 1605MHz		
	35@ 1710~ 1990MHz		
Attenuation (min.)	30@ 2170MHz		
	30@ 4800~ 4967MHz		
	25@ 5150 ~ 6000MHz		
	20@ 7200~ 7450.5MHz		
Operation Temperature Range	-40°C ~ +85°C		
Typical Electrical Chart			
-10102030305060506050 -	3 3.5 4 4.5 5 5.5 6 6.5 7 7.5 Frequency (GHz)		

SOLDER LAND PATTERN





RELIABILITY TEST

Test item Test condition / Test method		Specification
Solderability JIS C 0050-4.6	*Solder bath temperature : 235 ± 5°C	At least 95% of a surface of each terminal
JESD22-B102D	*Immersion time : 2 ± 0.5 sec	electrode must be covered by fresh solder.
	Solder : Sn3Ag0.5Cu for lead-free	
(Resistance to dissolution		Loss of metallization on the edges of each electrode shall not exceed 25%.
Resistance to soldering heat JIS C 0050-5.4	*Preheating temperature : 120~150°C,	No mechanical damage.
	1 minute.	Samples shall satisfy electrical specification
	*Solder temperature : 270±5°C *Immersion time : 10±1 sec	Loss of metallization on the edges of each
	Solder : Sn3Ag0.5Cu for lead-free	electrode shall not exceed 25%.
	Measurement to be made after keeping at room temperature for 24±2 hrs	
Drop Test JIS C 0044 Customer's specification.	*Height: 75 cm *Test Surface: Rigid surface of concrete or steel. *Times: 6 surfaces for each units; 2 times for each side.	No mechanical damage. Samples shall satisfy electrical specification after test.
Adhesive Strength of Termination JIS C 0051- 7.4.3	*Pressurizing force : 5N(≦0603) ; 10N(>0603) *Test time : 10±1 sec	No remarkable damage or removal of the termination.
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5±1	No mechanical damage. Samples shall satisfy electrical specification after test.
	sec. Measurement to be made after keeping at room temperature for 24±2 hours	

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Temperature cycle JIS C 0025	 30±3 minutes at -40°C±3°C, 10~15 minutes at room temperature, 30±3 minutes at +85°C±3°C, 10~15 minutes at room temperature, Total 100 continuous cycles Measurement to be made after keeping at room temperature for 24±2 hrs 	No mechanical damage. Samples shall satisfy electrical specification after test.
Vibration JIS C 0040	*Frequency: 10Hz~55Hz~10Hz(1min) *Total amplitude: 1.5mm *Test times: 6hrs.(Two hrs each in three mutually perpendicular directions)	No mechanical damage. Samples shall satisfy electrical specification after test.
High temperature JIS C 0021	*Temperature: 85°C±2°C *Test duration: 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test.
Humidity (steady conditions) JIS C 0022	*Humidity: 90% to 95% R.H. *Temperature: 40±2°C *Time: 1000+24/-0 hrs. Measurement to be made after keeping at room temperature for 24±2 hrs % 500hrs measuring the first data then 1000hrs data	No mechanical damage. Samples shall satisfy electrical specification after test.
Low temperature JIS C 0020	*Temperature : -40°C±2°C *Test duration : 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test.

SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

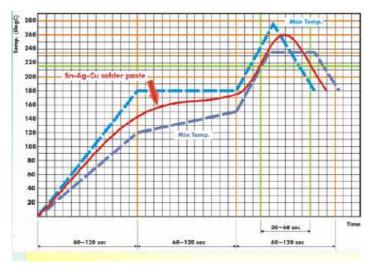


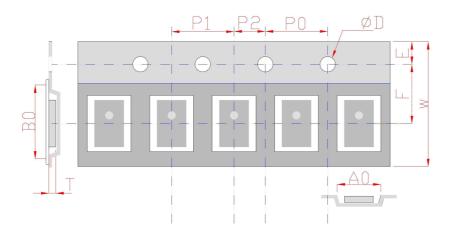
Fig 2. Infrared soldering profile

ORDERING CODE

RF	BPF	201208	0	Α	F	Т
Walsin	Product Code	Dimension code	Unit of	Application	Specification	Packing
RF	BPF:	Per 2 digits of	dimension	A: 2.4GHZ ISM	Design code	T : Reeled
device	Band Pass Filter	Length, Width,	0 : 0.1 mm	Band		
		Thickness :	1 : 1.0 mm			
		e.g. :				
		201208 =				
		Length 20,				
		Width 12,				
		Thickness 08				

Minimum Ordering Quantity: 2000 pcs per reel.

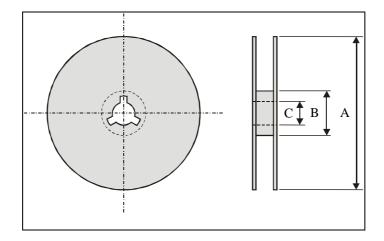
PACKAGING



Plastic Tape specifications (unit :mm)

Index	Ao	Во	ΦD	Т	W
Dimension (mm)	1.45 ± 0.10	2.25 ± 0.10	1.55 + 0.10	1.10 ± 0.10	8.0 ± 0.10
Index	E	F	Po	P1	P2
Dimension (mm)	1.75 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.10

Reel dimensions



Index	А	В	С
Dimension (mm)	Ф178.0	Ф60.0	Ф13.0

Taping Quantity: 2000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.

■ Temperature : -10 to +40°C

Humidity: 30 to 70% relative humidity

- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.